



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

1.MATERIAL:

HOUSING: PBT, BLACK, UL94V-0  
CONTACTS: 0.35[0.014] THICK PHOSPHOR BRONZE PLATED WITH  
100μ" MINIMUM THICK TIN IN SOLDER AREA.  
15μ" MINIMUM THICK GOLD IN LOCALIZED PLATE AREA.  
ENTIRE CONTACTS PLATED WITH 30μ" MINIMUM THICK NICKEL.

2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1688-F1

						UNIT SCALE SHEET mm[inch] 1 of 1		TITLE:	
		DRAWN BY				APPROVED BY		<b>RJ45, MODULAR JACK, 1X6, W/O LED, 8P, 8C, UNSHIELDED, THRU-HOLE</b>	
		董正一		董正一		2004.08.23			
				GENERAL TOLERANCE					
B1	REVISE	2005.12.30	X.X±0.25	ANGLE±					
B0	NEW RELEASE	2005.12.22	X.XX±0.15						
REV.	DESCRIPTION	DATE	X.XXX±0.05					DRAW NO. : HRJ800615-U1688-F1	
								REV. B1	